FED
Wir verbinden

Call for Papers

34th FED Conference
September 23 and 24, 2026
Bamberg

Design and Manufacturing of Electronic Assemblies

Strategies, solutions, and ideas for technology and organization

Printed circuit board and assembly design

Design for excellence in practice, printed circuit board technology, base material, layer structure, thermal management and thermal design, high-speed design, signal and power integrity, standards, tools, data quality, and best practices

Digital transformation, AI, and security

Practical use of AI in design and manufacturing, data models, data responsibility, transparency, cybersecurity in design, production and supply chain, limitations, risks, and lessons learned

Assembly manufacturing and EMS

Automation and AI support, digital processes and end-to-end data, printing and soldering processes, inspection and testing, productivity, quality, cost-effectiveness

Solutions for SMEs: Practice & Organization

Digital transformation in SMEs, skilled workers, qualification, knowledge transfer, work organization, leadership, collaboration, costs, time-to-market, make-or-buy

Assembly and connection technology

Advanced packaging and system integration, 3D integration and 3D design, best practices, miniaturization, embedding, 3D electronics, additive manufacturing processes

Strategy, regulation, and responsibility

Sustainable development and manufacturing, repair, service life, and recycling, standards, approvals, compliance, carbon footprint and digital product passport

We look forward to receiving your topic proposal by March 29, 2026.

Please submit a detailed description of your presentation topic online.
The speaking time for **non-promotional technical presentations** is 35 minutes; contributions can be submitted in **German or English**. A program committee decides on acceptance into the conference program.

Submit abstract: **fed-konferenz.de/cfp**

The FED Conference: Assembly Design Meets Manufacturing

The **FED Conference** is the central platform for everyone responsible for industrial electronics. It brings together PCB designers, PCB and assembly manufacturers, EMS and OEM companies, suppliers, and applied research to showcase, discuss, and further develop viable solutions for practical applications.

Over 300 experts engage in peer-to-peer discussions, sharing their experiences, solutions, and practical insights. Two conference days featuring technical presentations, discussions, keynotes, and an accompanying exhibition provide participants with the opportunity to learn about specific approaches, classify their own questions, and take away fresh ideas for their daily work.

With its **Call for Papers**, the FED invites you to actively participate in shaping the conference. We are looking for contributions that integrate electronics design and manufacturing and provide concrete insights into current challenges and solutions. The focus is on practical topics such as design for excellence, the practical use of AI in design and manufacturing processes, and sustainability throughout the entire product life cycle.

We welcome presentations that demonstrate what works and why: reports on experiences from industrial practice, best practices, and new approaches in technology and organization. The decisive factor is the added value for participants: providing guidance, transferability, and a realistic assessment of technical, organizational, and economic interdependencies.

The FED conference at a glance

Diverse topics: Technologies and processes for the design, manufacturing, and industrialization of printed circuit boards, assemblies, and systems
Audience: Developers, designers, manufacturing specialists, and decision-makers in direct exchange
Technical depth: Technical presentations and moderated expert panels in four dedicated tracks
Practical relevance: Accompanying trade exhibition for everyday development and manufacturing
Inspiration & dialogue: Keynotes with substance and an after-work event on September 23

Your benefits as a speaker

Relevant reach: Present your topic to a qualified audience of experts from industry and applied research.
Technical dialogue: Discuss your content directly with users, experts, and decision-makers.
Positioning: Strengthen your professional reputation through FED's conference marketing in trade media and social networks.
Appreciation: You are our guest on the conference day of your presentation and for the evening event on September 23 in Bamberg.

Facts, topics, and impressions of the FED conferences: fed-konferenz.de

Your contact

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Electronics Design and Manufacturing Association